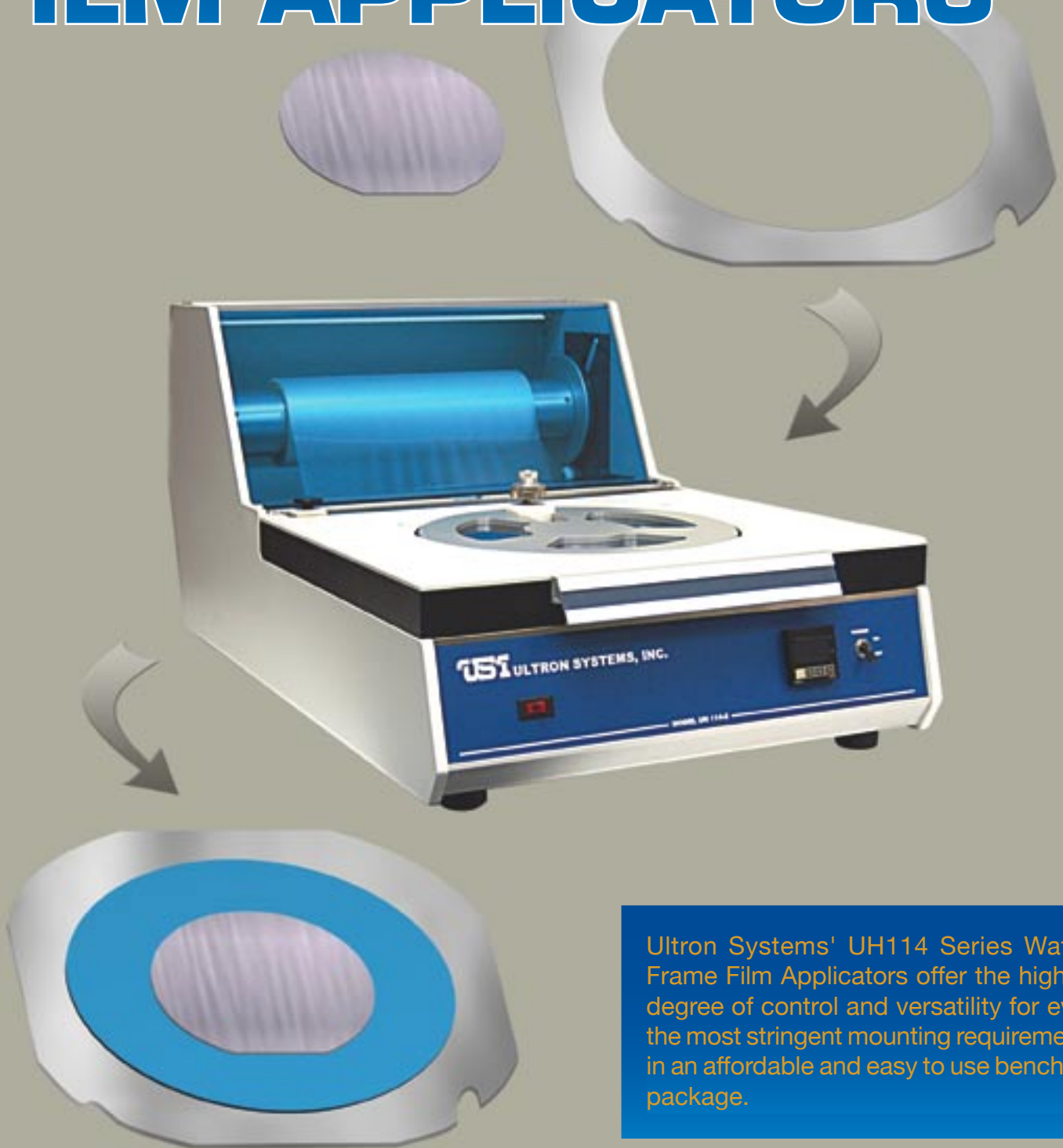


UH114

SERIES

WAFER/FRAME FILM APPLICATORS



Ultron Systems' UH114 Series Wafer/Frame Film Applicators offer the highest degree of control and versatility for even the most stringent mounting requirements in an affordable and easy to use benchtop package.



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UH114/UH114-8

The Models UH114 and UH114-8 set the benchmark for control and versatility. For dicing/sawing applications, uniform adhesive plastic film lamination is paramount. The mounters feature an easily adjustable spring-loaded roller assembly, along with film tensioner bars along both the x- and y-axes to assure bubble-free lamination of the film to the wafer and film frame. In addition, both models feature a retractable film cutting system with adjustable cutting pressure to accommodate various tape base materials and thicknesses. Roller pressure is adjusted from the topside of the units for different process requirements and to accommodate various wafer thicknesses. A digital temperature controller assures consistent workstage temperatures for repeatable mounting. Adjustable alignment pins and vacuum cups accommodate almost any type of film frame, including plastic. The workstage height is also adjustable relative to the frame height for different wafer thicknesses.

UH114-12

Based on the highly successful Models UH114/UH114-8 Wafer/Frame Film Applicators, the Model UH114-12 represents the next level of bubble-free film lamination of 300mm wafers to their respective film frames. The film unwinds along a new roller path so that "crease lines" (which are common to most film mounters and occur at the point the unwound film meets the film roll) are eliminated from the lamination area for the highest uniformity of adhesion in the mounting area.

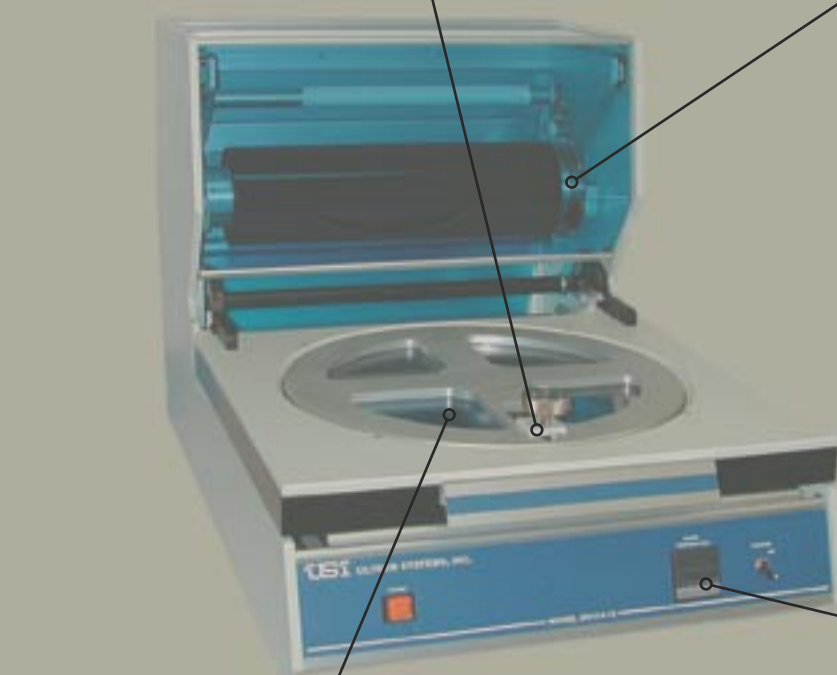
The Model UH114-12 features one-pass lamination which provides an extra margin of safety when mounting particularly fragile wafers/substrates. Most mounters laminate the film in two passes, i.e. one pass as the film is laminated to the film frame and wafer/substrate and a second relaminating pass as the roller returns to its home position. The Model UH114-12, however, laminates on the first pass only; the second pass is contact-free.

The mounter offers the highest degree of control and versatility to meet even the most stringent process requirements. The film tension is adjustable to accommodate almost any semiconductor adhesive plastic film available. In addition, the workstage height is adjustable from the top of the unit to quickly adapt to wafers/substrates of varying thicknesses. With the Model UH114-12 Wafer/Frame Film Mounter, operator variables have been virtually eliminated.

Rotary Cutting Wheel



Gear-driven Take-up Roller



Digital Temperature Controller



Workstage w/Teflon-coated chuck and adjustable alignment pins

STANDARD FEATURES

- Single-pass lamination (114-12 only)
- Workstage height adjustable from top of unit
- Accommodates film/protective layer wound on the outside or inside

OPTIONS

- Edge-Contact Workstage
- Static Ionization Bar w/power safety interlock
- Gear-driven Take-up Roller Assembly
- Rotary Cutting Wheel for prolonged blade life

SPECIFICATIONS

MODEL UH114

Height: 15.5 inches
Width: 14.5 inches
Depth: 28.0 inches
Weight: 62 lbs.

UH114-8

Height: 15.5 inches
Width: 19.25 inches
Depth: 32.5 inches
Weight: 81 lbs.

Model UH114-12

Height: 21.25 inches
Width: 21.50 inches
Depth: 34.50 inches
Weight: 129 lbs.

SERVICE REQUIREMENTS

Vacuum: 25" Hg.
Voltage: 115VAC, 4A



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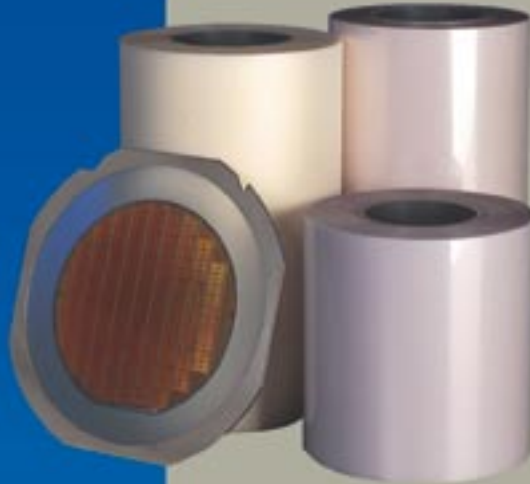
Other Ultron Products

**Models UH130/
UH130-12
Die-Matrix
Expanders**



Defines the standard in die presentation through precise control of die separation process parameters. Better die presentation results in higher throughput and increased yield. The UH130 series facilitates this by maintaining die orientation and consistent die spacing.

**UV Adhesive
Plastic Film
Series**



Has the advantage of high adhesive strength -- for the securing of wafers/substrates during sawing -- which is significantly reduced after UV light exposure to facilitate die removal. We are proud to offer the widest selection of UV film available to meet your process requirements.

**Models
UH102/UH102-12
UV Curing
Systems**



Are inexpensive solutions for the curing of UV film, yet do not compromise control or versatility. They include a nitrogen blanket to assure complete curing of the UV adhesive, a microprocessor-based programmable controller, a lamp intensity measurement port, and a serpentine-style grid lamp for even, consistent UV-exposure.



ULTRON SYSTEMS, INC.

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